

Process and device for polishing semiconductor wafers

Abstract

The invention relates to a process for polishing semiconductor wafers, in which at least one side of at least one semiconductor wafer is pressed against a polishing plate, over which a polishing cloth is stretched, and is polished, the semiconductor wafer and the polishing plate executing a relative movement. During the polishing, the semiconductor wafer passes over at least two regions on the polishing plate, which regions have defined radial widths and are at different temperatures. Temperature-control means are provided in the polishing plate, with the aid of which the number, the radial widths and the temperatures of the regions are fixed before the semiconductor wafers are polished. The invention furthermore relates to a device for carrying out the process.

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